CareerCross by JAC Recruitment

PR/158747 | Field Service Engineer

Job Information

Recruiter
JAC Recruitment Malaysia

Job ID
1540941

Industry
Other (Manufacturing)

Job Type
Permanent Full-time

Location
Malaysia

Salary
Negotiable, based on experience

Refreshed
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General Requirements

Minimum Experience Level
Over 3 years

Career Level
Mid Career

Minimum English Level
Business Level

Minimum Japanese Level
Business Level

Minimum Education Level
Associate Degree/Diploma

Visa Status
No permission to work in Japan required

Job Description

An established MNC in wafer packaging industry, seeking talented individuals with an innovative mindset to join their Engineering team. You will be a key part of revolutionary in the advanced packaging equipment for automated and high precision manufacturing industries.

JOB DESCRIPTIONS

- Perform troubleshooting, installation, process evaluation, setup, maintenance/preventive maintenance, field modifications, and repair on designated equipment,
- Order and manage repair part cycle time.
- Maintain customer service log and internal service records in a timely manner.
- Maintain daily communication with customers to ensure issue resolution and proper follow up.
- Maintain tools and test equipment to ensure proper calibration.
- Adhere to requirements such as HIPPA, OSHA, FDA, etc

JOB REQUIREMENTS

- Min Bachelor’s Degree in related Engineering field.
- Min 3 years of working experience as process, field service, or application engineering in semiconductor industries.
- Experience in thin film deposition, SMT, Cu-RDL / Cu-Pillar, or WLP.
- Familiar with FMEA, Control Plan, SPC, WI, etc.
- Possess own transport.

- Willing and able to travel in short notice.
- Ability to lift and carry toolbox weighing up to 5lbs.

Company Description